

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	RELEASE BY SECURED PARTY

**CONVEYING PARTY DATA**

Name	Execution Date
Hercules Technology Growth Capital, Inc.	06/10/2011

**RECEIVING PARTY DATA**

<b>Name:</b>	Nexx Systems, Inc., a Delaware Corporation
<b>Street Address:</b>	900 Middlesex Turnpike
<b>Internal Address:</b>	Building 6
<b>City:</b>	Billerica
<b>State/Country:</b>	MASSACHUSETTS
<b>Postal Code:</b>	01821

**PROPERTY NUMBERS Total: 14**

Property Type	Number
Application Number:	10971726
Application Number:	11155008
Patent Number:	6174011
Patent Number:	6217272
Patent Number:	6251250
Patent Number:	6328858
Patent Number:	6396024
Patent Number:	6530733
Patent Number:	6540899
Patent Number:	6682288
Patent Number:	6821912
Patent Number:	7100954
Patent Number:	7722747
Patent Number:	7445697

**CH \$560.00 10971726**

**CORRESPONDENCE DATA**

Fax Number: (313)496-8454  
Phone: 3134967562  
Email: spano@millercanfield.com

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.*

Correspondent Name: Kristen I. Spano  
Address Line 1: 150 West Jefferson Avenue  
Address Line 2: Suite 2500  
Address Line 4: Detroit, MICHIGAN 48226

<b>ATTORNEY DOCKET NUMBER:</b>	125055-810
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<b>NAME OF SUBMITTER:</b>	Kristen I. Spano
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**Total Attachments: 2**

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REASSIGNMENT AND RELEASE OF SECURITY INTEREST

This Reassignment and Release of Security Interest is made as of June 10, 2011 by **Hercules Technology Growth Capital, Inc.** ("Secured Party") in favor of **Nexx Systems, Inc.**, a Delaware corporation ("Grantor"), with its principal place of business at 900 Middlesex Turnpike, Building 6, Billerica, Massachusetts 01821.

Grantor has collaterally assigned certain interests in the patents described on Exhibit A ("Patents") to Secured Party under the Loan and Security Agreement dated as of December 19, 2006, and recorded with the United States Patent and Trademark Office as set forth on Exhibit A.

Secured Party hereby releases its security interest in the Patents and reassigns to Grantor, without warranty or recourse, all interest of Secured Party in the Patents.

**Hercules Technology Growth Capital, Inc.**


By:   
Name: K. Nicholas Marlitsch  
Its: Associate General Counsel

EXHIBIT A  
Patents

<u>Patent / Application Number</u>	<u>Recordation Date</u>	<u>Reel/Frame Number</u>	<u>Description</u>
10/971,726	11/05/07	020064/0111	Method and apparatus for fluid processing a workpiece
11/155,008	11/05/07	020064/0111	Method and apparatus for fluid processing and drying a workpiece
6,174,011	11/05/07	020064/0111	Method and apparatus for handling thin and flat workpieces and the like
6,217,272	11/05/07	020064/0111	In-Line sputter deposition system
6,251,250	11/05/07	020064/0111	Method of and apparatus for controlling fluid flow and electric fields involved in the electroplating of substantially flat workpieces and the like and more generally controlling fluid flow in the processing of other workpiece surfaces as well
6,328,858	11/05/07	020064/0111	Multi-layer sputter deposition apparatus
6,396,024	11/05/07	020064/0111	Permanent magnet ECR plasma source with integrated multipolar magnetic confinement
6,530,733	11/05/07	020064/0111	Substrate processing pallet and related substrate processing method and machine
6,540,899	11/05/07	020064/0111	Method of and apparatus for fluid sealing, while electronically contacting, wet-processed workpieces
6,682,288	11/05/07	020064/0111	Substrate processing pallet and related substrate processing method and machine
6,821,912	11/05/07	020064/0111	Substrate processing pallet and related substrate processing method and machine
7,100,954	11/05/07	020064/0111	Ultra-thin wafer handling system
7,722,747	11/05/07	020064/0111	Method and apparatus for fluid processing a workpiece
7,445,697	11/05/07	020064/0111	Method and apparatus for fluid processing a workpiece